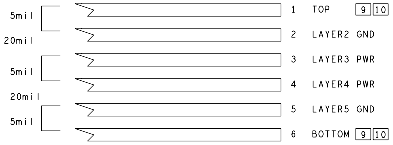
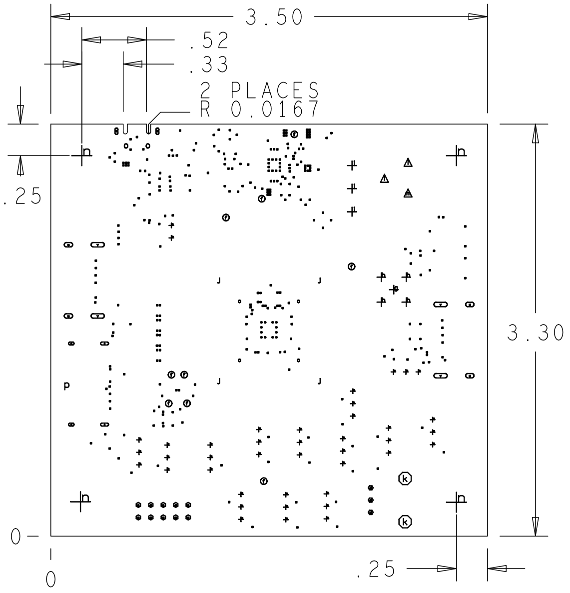
DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
╋	160.0	+3.0/-3.0	PLATED	4
▲	140.0	+3.0/-3.0	PLATED	1
△	120.0	+3.0/-3.0	PLATED	2
ⓚ	98.0	+3.0/-3.0	PLATED	2
J	90.55	+3.0/-3.0	PLATED	4
╫	73.0	+3.0/-3.0	PLATED	3
+	62.99	+2.99/-2.99	PLATED	4
+	59.06	+2.99/-2.99	PLATED	1
ⓟ	52.0	+3.0/-3.0	PLATED	9
●	40.0	+3.0/-3.0	PLATED	10
●	39.0	+3.0/-3.0	PLATED	3
+	38.0	+3.0/-3.0	PLATED	41
·	12.0	+0.0/-12.0	PLATED	12
·	8.0	+0.0/-8.0	PLATED	302
P	55.12	+1.97/-1.97	NON-PLATED	1
•	41.34	+1.0/-1.0	NON-PLATED	4
⊂⊃	106.3x35.43	+1.97/-1.97	PLATED	4
⊂⊃	66.93x35.43	+3.15/-3.15	PLATED	4
∞	62.99x23.62	+1.97/-1.97	PLATED	2
8	51.18x23.62	+1.97/-1.97	PLATED	2
∞	43.31x23.62	+1.97/-1.97	PLATED	2
∘	33.46x25.59	+3.15/-3.15	PLATED	2





ALL DIMENSIONS ARE IN INCHES

GENERAL NOTES. UNLESS OTHERWISE SPECIFIED

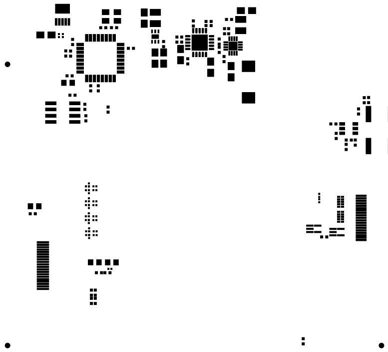
1. ALL FABRICATION ITEMS MUST MEET OR EXCEED BEST INDUSTRY PRACTICE : IPC-A-600C (Commercial std.)
2. LAMINATE MATERIAL : FR4 POLYCLAD 370 or EQUIVALENT
3. COPPER WEIGHT : 1oz START INTERNAL, 1/2oz START EXTERNAL
4. FINISHED BOARD THICKNESS : .062" +/- 10%
5. MAXIMUM WARP AND TWIST TO BE : .005 INCH PER INCH
6. MINIMUM COPPER WALL THICKNESS OF PLATED-THRU HOLES TO BE .001 INCH. THERE MUST BE 1MIL OR GREATER PLATING ON EACH SIDE OF THE BARREL WHEN VIEWED IN THE CROSS SECTION
7. MINIMUM ANNULAR RING OF PLATED-THRU HOLES TO BE .002 INCH
8. MAXIMUM ALLOWABLE LINE REDUCTION TO BE 20% OR .002" WHICHEVER IS SMALLER
9. 0.005" SIGNAL LINES WITH 0.006" SPACING ON LAYER 1 & 6 TO BE IMPEDANCE CONTROLLED 100 OHMS DIFFERENTIAL +/- 5%
10. 0.008" SIGNAL LINES ON LAYER 1 & 6 TO BE IMPEDANCE CONTROLLED 50 OHMS +/- 5%
11. DIELECTRIC CONSTANTS ARE CORE : 4.1
PREPREG : 4.1
12. SOLDERMASK CLEARANCE IS GIVEN AS SAME AS PAD SIZE FOR ALL SMT COMPONENT. VENDOR SHALL OVERSIZE THE MASK CLEARANCES AS PER THEIR MANUFACTURE CAPABILITIES.
13. 0.008" AND 0.012" DRILL VIAS NEED TO BE TENTED FROM BOTH SIDE.

PROCESS NOTES

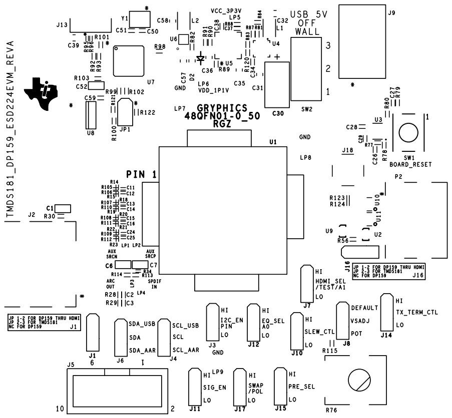
1. CIRCUITRY ON OUTER LAYERS TO BE PLATED WITH : ENIG
2. SOLDERMASK BOTH SIDES PER ARTWORK : GREEN LPI
3. SILKSCREEN BOTH SIDES PER ARTWORK : COLOR = WHITE

4. ALL BOARDS MUST MEET OT EXCEEED UL94-V0 REQUIRMENTS.
PCB MUST BEAR THE UL094-0-UL REGISTERD MATERIAL ID NUMBER

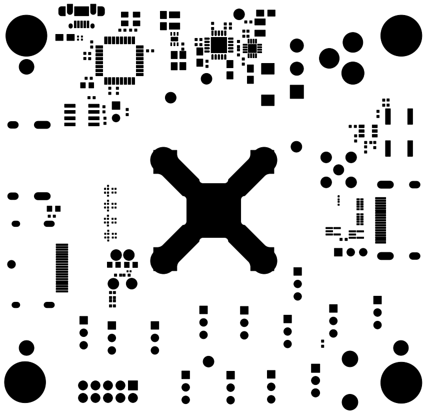
krypton solutions	BOARD NAME: TMDS181_DP159_ESD2X4EVM_REVA	BOARD REV: 1.0	KSID: XXXXX	JOB NUMBER: XXXXXX
	ALL ARTWORK LAYERS VIEWED FROM TOP	LAYER DESCRIPTION: LAYER 13 - FAB		



krypton solutions	BOARD NAME: TMDS181_DP159_ESD2X4EVM_REVA	BOARD REV: 1.0	KSID: XXXXX	JOB NUMBER: XXXXXX
	ALL ARTWORK LAYERS VIEWED FROM TOP	LAYER DESCRIPTION: LAYER 9 - SOLDERPASTE TOP		



krypton solutions	BOARD NAME: TMDS181_DP159_ESD2X4EVM_REVA BOARD REV: 1.0	KSID: XXXXX	JOB NUMBER: XXXXXX
	ALL ARTWORK LAYERS VIEWED FROM TOP	LAYER DESCRIPTION: LAYER 11 - SILKSCREEN TOP	



krypton
solutions

BOARD NAME:
TMDS181_DP159_ESD2X4EVM_REVA

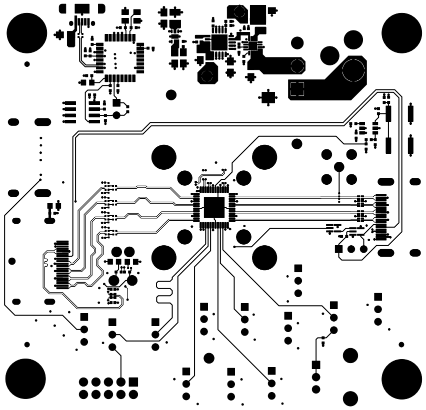
BOARD REV:
1.0

KSID:
XXXXX

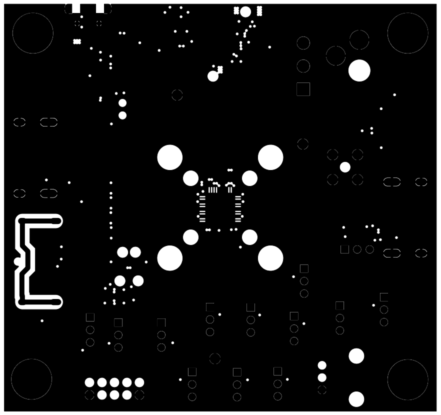
JOB NUMBER:
XXXXXX

ALL ARTWORK LAYERS VIEWED FROM TOP

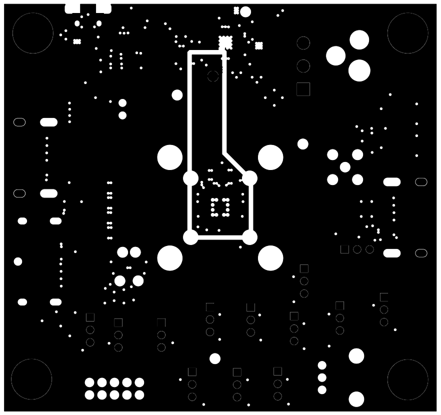
LAYER DESCRIPTION:
LAYER 7 - SOLDERMASK TOP



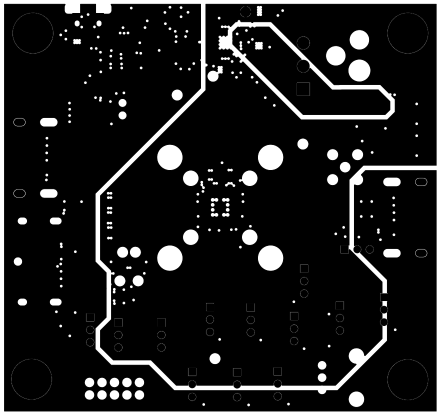
krypton solutions	BOARD NAME: TMDS181_DP159_ESD2X4EVM_REVA	BOARD REV: 1.0	KSID: XXXXX	JOB NUMBER: XXXXXX
	ALL ARTWORK LAYERS VIEWED FROM TOP	LAYER DESCRIPTION: LAYER 1 - TOP		



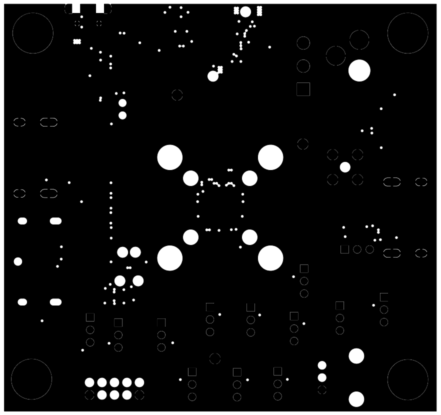
BOARD NAME: TMDS181_DP159_ESD2X4EVM_REVA	BOARD REV: 1.0	KSID: XXXXX	JOB NUMBER: XXXXXX
ALL ARTWORK LAYERS VIEWED FROM TOP	LAYER DESCRIPTION: LAYER 2 - GND		



krypton solutions	BOARD NAME: TMDS181_DP159_ESD2X4EVM_REVA	BOARD REV: 1.0	KSID: XXXXX	JOB NUMBER: XXXXXX
	ALL ARTWORK LAYERS VIEWED FROM TOP	LAYER DESCRIPTION: LAYER 3 - PWR		



BOARD NAME: TMDS181_DP159_ESD2X4EVM_REVA	BOARD REV: 1.0	KSID: XXXXX	JOB NUMBER: XXXXXX
ALL ARTWORK LAYERS VIEWED FROM TOP	LAYER DESCRIPTION: LAYER 4 - PWR		



krypton solutions

BOARD NAME: TMDS181_DP159_ESD2X4EVM_REVA

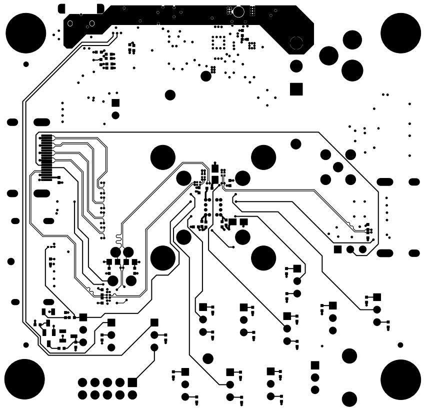
BOARD REV: 1.0

KSID: XXXXX

JOB NUMBER: XXXXXX

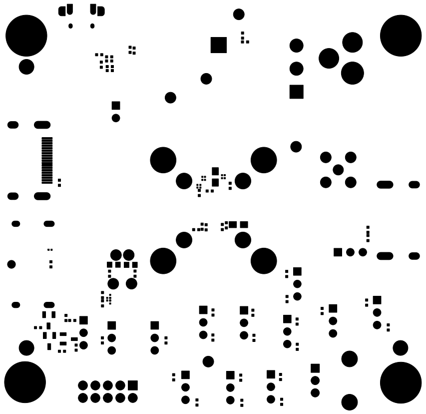
ALL ARTWORK LAYERS VIEWED FROM TOP

LAYER DESCRIPTION: LAYER 5 - GND

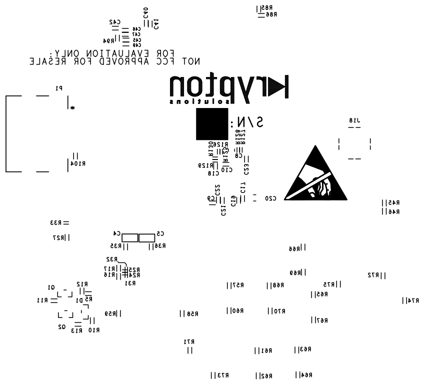


krypton solutions

BOARD NAME: TMDS181_DP159_ESD2X4EVM_REVA	BOARD REV: 1.0	KSID: XXXXX	JOB NUMBER: XXXXXX
ALL ARTWORK LAYERS VIEWED FROM TOP	LAYER DESCRIPTION: LAYER 6 - BOTTOM		



krypton solutions	BOARD NAME: TMDS181_DP159_ESD2X4EVM_REVA	BOARD REV: 1.0	KSID: XXXXX	JOB NUMBER: XXXXXX
	ALL ARTWORK LAYERS VIEWED FROM TOP	LAYER DESCRIPTION: LAYER 8 - SOLDERMASK BOTTOM		



BOARD NAME: TMDS181_DP159_ESD2X4EVM_REVA	BOARD REV: 1.0	KSID: XXXXX	JOB NUMBER: XXXXXX
ALL ARTWORK LAYERS VIEWED FROM TOP	LAYER DESCRIPTION: LAYER 12 - SILKSCREEN BOTTOM		

krypton solutions

BOARD NAME: TMDS181_DP159_ESD2X4EVM_REVA

BOARD REV: 1.0

KSID: XXXXX

JOB NUMBER: XXXXXX

ALL ARTWORK LAYERS VIEWED FROM TOP

LAYER DESCRIPTION: LAYER 10 - SOLDERPASTE BOTTOM

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